Quad Bus Driver/Receiver with 2-to-1 Output **Multiplexers**

Description

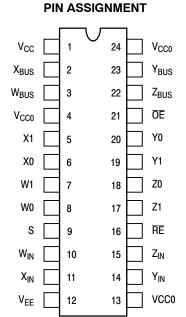
The MC10H330 is a Quad Bus Driver/Receiver with two-to-one output multiplexers. These multiplexers have a common select and output enable. When disabled, (\overline{OE} = high) the bus outputs go to -2.0 V. Their output can be brought to a low state (V_{OL}) by applying a high level to the receiver enable (\overline{RE} = High). The parameters specified are with 25 Ω loading on the bus drivers and 50 Ω loads on the receivers.

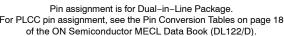


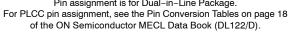
- Propagation Delay, 1.5 ns Typical Data-to-Output
- Improved Noise Margin 150 mV (Over Operating Voltage and Temperature Range)

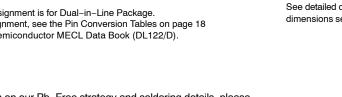
DIP

- Voltage Compensated
- MECL 10K[™] Compatible
- Pb-Free Packages are Available*









*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



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MARKING DIAGRAMS*





CDIP-24 L SUFFIX **CASE 758**





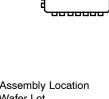
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PDIP-24 **P SUFFIX CASE 724**



10H330G AWLYYWW

PLCC-28 **P SUFFIX CASE 776**



Α	= Assembly Location
WL	= Wafer Lot
YY	= Year
WW	= Work Week
G	= Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

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Table 1. MAXIMUM RATINGS

Symbol	Characteristic	Rating	Unit
V_{EE}	Power Supply (V _{CC} = 0)	-8.0 to 0	Vdc
VI	Input Voltage (V _{CC} = 0)	0 to V _{EE}	Vdc
l _{out}	Output Current – Continuous – Surge	50 100	mA
T _A	Operating Temperature Range	0 to +75	°C
T _{stg}	Storage Temperature Range – Plastic – Ceramic	−55 to +150 −55 to +165	°C ℃

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

Table 2. ELECTRICA	_ CHARACTERISTICS	6 (V _{EE} = -5.2 V ±5%) (Note 1)
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		0 °		25 °		75 °		
Symbol	Characteristic	Min	Max	Min	Max	Min	Max	Unit
١ _E	Power Supply Current	-	157	-	143	-	157	mA
l _{inH}	Input Current High Pins 5–8, 17–20 Pins 16, 21 Pin 9	- - -	667 514 475		417 321 297	- - -	417 321 297	μΑ
I _{inL}	Input Current Low	0.5	-	0.5	-	0.3	-	μΑ
V _{OH}	High Output Voltage	-1.02	-0.84	-0.98	-0.81	-0.92	-0.735	Vdc
V _{OL}	Low Output Voltage	-1.95	-1.63	-1.95	-1.63	-1.95	-1.60	Vdc
V _{IH}	High Input Voltage	-1.17	-0.84	-1.13	-0.81	-1.07	-0.735	Vdc
V _{IL}	Low Input Voltage	-1.95	-1.48	-1.95	-1.48	-1.95	-1.45	Vdc

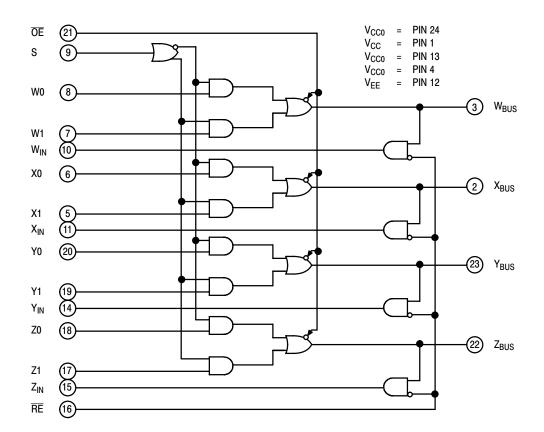
1. Each MECL 10H[™] series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 lfpm is maintained. Receiver outputs are terminated through a 50 Ω resistor to −2.0 Vdc. Bus outputs are terminated through a 25 Ω resistor to −2.0 Vdc.

Table 3. AC PARAMETERS

		0	0	2	5°	7	75°	
Symbol	Characteristic	Min	Max	Min	Max	Min	Max	Unit
t _{pd}	Propagation Delay							ns
	Select-to-Input	1.8	5.3	1.8	5.3	1.8	5.3	
	Data-to-Bus Output	0.5	2.0	0.5	2.0	0.5	2.0	
	Select-to-Bus							
	Output	1.0	3.2	1.0	3.2	1.0	3.2	
	OE-to-Bus Output	0.8	2.2	0.8	2.2	0.8	2.2	
	Bus-to-Input	0.8	2.1	0.8	2.1	0.8	2.4	
	RE-to-Input	0.5	2.2	0.5	2.2	0.5	2.2	
	Data-to-Receiver							
	Input	1.3	4.0	1.3	4.0	1.3	4.0	
t _r	Rise Time	0.5	2.0	0.5	2.0	0.5	2.0	ns
t _f	Fall Time	0.5	2.0	0.5	2.0	0.5	2.0	ns

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

LOGIC DIAGRAM



MULTIPLEXER TRUTH TABLE

ŌE	S	W _{Bus}	X _{Bus}	Y _{Bus}	Z _{Bus}
H	X	-2.0 V	-2.0 V	-2.0 V	-2.0 V
L	L	W0	X0	Y0	Z0
L	H	W1	X1	Y1	Z1

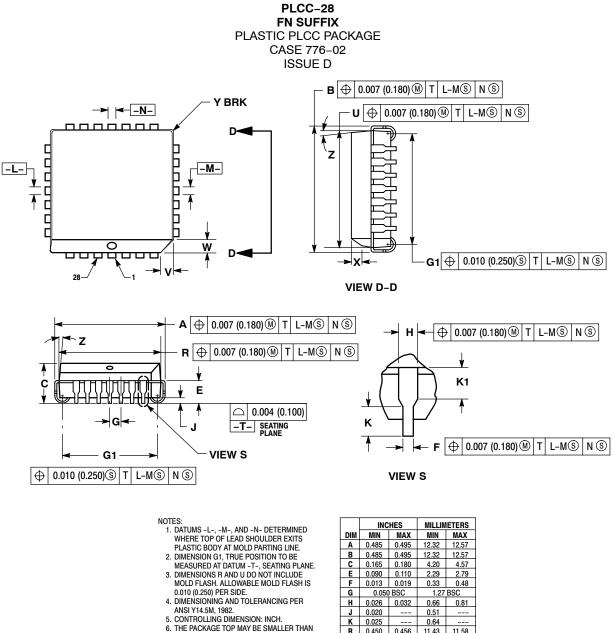
RECEIVER TRUTH TABLE

RE	W _{in}	X _{in}	Y _{in}	Z _{in}
Н	L	L	L	L
L	W _{Bus}	X _{Bus}	Y _{Bus}	Z _{Bus}

ORDERING INFORMATION

Device	Package	Shipping [†]
MC10H330FN	PLCC-28	37 Units / Rail
MC10H330FNG	PLCC-28 (Pb-Free)	37 Units / Rail
MC10H330FNR2	PLCC-28	500 / Tape & Reel
MC10H330FNR2G	PLCC-28 (Pb-Free)	500 / Tape & Reel
MC10H330L	CDIP-24	15 Unit / Rail
MC10H330P	PDIP-24	15 Unit / Rail
MC10H330PG	PDIP-24 (Pb-Free)	15 Unit / Rail

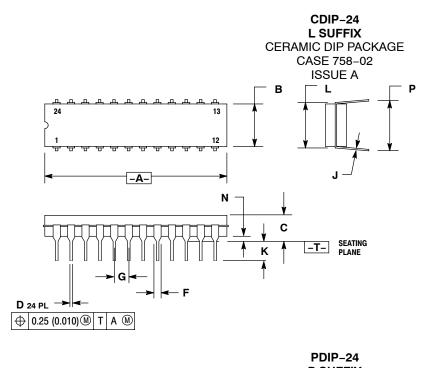
PACKAGE DIMENSIONS



- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE DLASTIC PODY PLASTIC BODY.
- PLASTIC BODY. 7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.485	0.495	12.32	12.57
В	0.485	0.495	12.32	12.57
С	0.165	0.180	4.20	4.57
Е	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	BSC	1.27	BSC
Н	0.026	0.032	0.66	0.81
J	0.020		0.51	
K	0.025		0.64	
R	0.450	0.456	11.43	11.58
U	0.450	0.456	11.43	11.58
۷	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y		0.020		0.50
Z	2 °	10°	2 °	10°
G1	0.410	0.430	10.42	10.92
K1	0.040		1.02	

PACKAGE DIMENSIONS



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

CONTROLLING DIMENSION: INCH.
DIMENSION L TO CENTER OF LEADS WHEN

FORMED PARALLEL.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	1.240	1.285	31.50	32.64
В	0.285	0.305	7.24	7.75
С	0.160	0.200	4.07	5.08
D	0.015	0.021	0.38	0.53
F	0.045	0.062	1.14	1.57
G	0.100) BSC	2.54 BSC	
J	0.008	0.013	0.20	0.33
Κ	0.100	0.165	2.54	4.19
L	0.300	0.310	7.62	7.87
Ν	0.020	0.050	0.51	1.27
Р	0.360	0.400	9.14	10.16

P SUFFIX PLASTIC DIP PACKAGE CASE 724-03 -A-**ISSUE D** <u> ጉ ጉ ጉ</u> -B С NOTE 1 -Tκ SEATING М E J 24 PL G F \oplus 0.25 (0.010) M T B M D 24 PI \oplus 0.25 (0.010) M T A M

NOTES:

1. CHAMFERED CONTOUR OPTIONAL. 2. DIMENSION L TO CENTER OF LEADS WHEN

2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.

3. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

4. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIN	ETERS
DIM	MIN	MAX	MIN	MAX
Α	1.230	1.265	31.25	32.13
В	0.250	0.270	6.35	6.85
С	0.145	0.175	3.69	4.44
D	0.015	0.020	0.38	0.51
Е	0.050 BSC		1.27 BSC	
F	0.040	0.060	1.02	1.52
G	0.100	BSC	2.54 BSC	
J	0.007	0.012	0.18	0.30
K	0.110	0.140	2.80	3.55
Г	0.300 BSC		7.62	BSC
Μ	0°	15°	0°	15°
Ν	0.020	0.040	0.51	1.01

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